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WHAT IS CLAIMED IS:

1. A polishing body having a polishing part with a predetermined shape molded a residue or a dried powder prepared by eliminating a dispersion medium from an aqueous dispersion wherein a matrix material and abrasive are dispersed and contained respectively.
2. The polishing body according to Claim 1, wherein method for eliminating said dispersion medium is spray drying method.
3. The polishing body according to Claim 1, wherein the polishing body is used for the polishing of semiconductors.
4. A polishing body having a polishing part with a predetermined shape molded a residue or a dried powder prepared by eliminating a dispersion medium from an aqueous dispersion containing dispersed composite particles wherein abrasive is attached to a matrix material.
5. The polishing body according to Claim 4, wherein method for eliminating said dispersion medium is spray drying method.
6. The polishing body according to Claim 4, further a matrix material and/or abrasive are dispersed and contained in said aqueous dispersion.
7. The polishing body according to Claim 4, wherein the respective zeta potentials of said matrix material and said abrasive are opposite in sign and the difference of said zeta potentials is 5mV or more.

8. The polishing body according to Claim 4, wherein the polishing body is used for the polishing of semiconductors.

9. A polishing body having a polishing part which is molded a residue or a dried powder prepared by eliminating a dispersion medium from an aqueous dispersion wherein a matrix material comprised of a crosslinkable polymer and abrasive are dispersed and contained respectively, which is crosslinked during drying said dispersion medium, or during molding, or after molding, and which has a crosslinked structure.

10. The polishing body according to Claim 9, wherein method for eliminating said dispersion medium is spray drying method.

11. The polishing body according to Claim 9, wherein the polishing body is used for the polishing of semiconductors.

12. A polishing body having a polishing part which is molded a residue or a dried powder prepared by eliminating a dispersion medium from an aqueous dispersion containing dispersed composite particles wherein abrasive is attached to a matrix material comprised of a crosslinkable polymer, which is crosslinked during drying said dispersion medium, or during molding, or after molding, and which has a crosslinked structure.

13. The polishing body according to Claim 12, wherein method for eliminating said dispersion medium is spray drying method.

14. The polishing body according to Claim 12, wherein the respective zeta potentials of said matrix material and said abrasive are opposite in sign and the difference of said zeta potentials is 5mV or more.

15. The polishing body according to Claim 12, wherein the polishing body is used for the polishing of semiconductors.